

L Number	Hits	Search Text	DB	Time stamp
1	30	@ad<=20010131 and 'SOI' same 'separation' and 'pressure' with 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 14:08
2	75	'SOI' same 'separation' and 'pressure' with 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 14:08
13	950	@ad<=20010131 and (438/464).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:40
14	359	@ad<=20010131 and (438/460).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:56
15	196	@ad<=20010131 and (438/461).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:56
16	361	@ad<=20010131 and (438/462).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:56
17	42	@ad<=20010131 and (438/463).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:56
18	479	@ad<=20010131 and (438/465).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:57
19	404	@ad<=20010131 and (257/620).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:57
20	524	@ad<=20010131 and (438/113-114).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 16:01
21	122	@ad<=20010131 and (438/311).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 16:01
22	711	@ad<=20010131 and (438/479).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 16:02
23	55	@ad<=20010131 and (438/480).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 16:02
24	180	@ad<=20010131 and (438/481).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 16:03

25	202	@ad<=20010131 and (438/910).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 16:03
-	1	Kiyofumi-Sakaguchi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/28 08:02
-	12780	Sakaguchi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:27
-	151	Sakaguchi-Kiyofumi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:36
-	2561	((257/620) or (438/460-465)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:17
-	1	"20020102758"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 12:55
-	434	((((257/620) or (438/460-465)).CCLS.) and @ad<=20010131 and 'scribe')	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 14:42
-	31	@ad<=20010131 and 'dicing' and 'separation' with 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 08:12
-	12	((((257/620) or (438/460-465)).CCLS.) and @ad<=20010131 and 'scribe') and 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:38
-	704	@ad<=20010131 and 'semiconductor' and 'kerf'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 14:59
-	88	@ad<=20010131 and 'semiconductor' and 'kerf' and 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 10:07
-	1	@ad<=20010131 and 'dicing' and 'separation' near 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 10:07
-	318	@ad<=20010131 and (438/462).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:27
-	14	@ad<=20010131 and (438/462).ccls. and fluid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 15:54

-	181	@ad<=20010131 and (438/462).ccls. and 'separated'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:04
-	70042	@ad<=20010131 and 'separation' with 'liquid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:17
-	84	@ad<=20010131 and 'separation' with 'high pressure fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:11
-	252108	(("438") or ("257")).CLAS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 16:19
-	998	@ad<=20010131 and 'thin-film semiconductor'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 08:17
-	15	(@ad<=20010131 and 'thin-film semiconductor') and 'dicing'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 08:18
-	136	'semiconductor' and 'die separation'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 08:26
-	426	'wafer' and 'dicing method'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 09:10
-	1	"5149586".PN.	USPAT	2002/10/18 08:36
-	1	"5281473".PN.	USPAT	2002/10/18 08:36
-	1	"5525422".PN.	USPAT	2002/10/18 08:37
-	1	"6176966".PN.	USPAT	2002/10/18 08:38
-	6	'wafer' and 'dicing method' with 'pressure'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 09:06
-	85	Sakaguchi-Kiyofumi.in. and apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 10:22
-	1	"20020100941"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/28 08:02
-	896	@ad<=20010131 and 'scribe' and 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 09:31

-	20	@ad<=20010131 and (438/464).ccls. and 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 09:55
-	143	@ad<=20010131 and 'scribe' and 'fluid' and 'crack'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 09:31
-	121	@ad<=20010131 and (438/464).ccls. and 'crack'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:39
-	335	@ad<=20010131 and (438/460).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:55
-	194	@ad<=20010131 and (438/461).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:55
-	331	@ad<=20010131 and (438/462).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:56
-	40	@ad<=20010131 and (438/463).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:56
-	932	@ad<=20010131 and (438/464).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 11:58
-	471	@ad<=20010131 and (438/465).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:56
-	386	@ad<=20010131 and (257/620).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:56
-	496	@ad<=20010131 and (438/113-114).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/17 13:45
-	396	@ad<=20010131 and (257/620).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/17 13:41
-	509	@ad<=20010131 and (438/113-114).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 15:56
-	347	@ad<=20010131 and (438/460).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/17 13:42

-	277	@ad<=20010131 and (438/458).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/17 13:43
-	509	@ad<=20010131 and (438/113-114).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/17 13:46
-	222	Sakaguchi-Kiyofumi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:44
-	514	Yonehara-Takao.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:43
-	2	"20040082149"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:42
-	33	Yonehara-Takao.in. and 'anodizing' and 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:44
-	70	Sakaguchi-Kiyofumi.in. and 'anodizing' and 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:44
-	62	Sakaguchi-Kiyofumi.in. and 'anodizing' and 'pressure' with 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:44
-	490	@ad<=20010131 and 'semiconductor' and 'notch' and 'pressure' with 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 10:09
-	8	@ad<=20010131 and 'separation' with 'semiconductor' and 'notch' and 'pressure' with 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:58
-	1	'JP 11317509'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 10:23
-	1	'JP11317509'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 10:22
-	1	'11317509'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:29
-	1	'JP11317509'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:30

-	1	'JP11039261'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:30
-	90	@ad<=20010131 and 'separation' with 'semiconductor' and 'open' and 'pressure' with 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:59
-	2	@ad<=20010131 and 'separation' with 'semiconductor' and 'kerf' and 'pressure' with 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:59
-	8	@ad<=20010131 and 'separation' with 'semiconductor' and 'notch' and 'pressure' with 'fluid'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/04 14:07